



Material Content Data Sheet



Sales Product Name	ESD5V5S1B-02LRH E6327			Issued		29. August 2013		
MA#	MA001032628							
Package	PG-TSLP-2-17			Weight*		0.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.14		1401	
	noble metal	gold	7440-57-5	0.004	0.54		5434	
	inorganic material	silicon	7440-21-3	0.020	2.68	3.36	26847	33682
leadframe	non noble metal	nickel	7440-02-0	0.276	37.00	37.00	369981	369981
wire	noble metal	gold	7440-57-5	0.012	1.60	1.60	16036	16036
encapsulation	organic material	carbon black	1333-86-4	0.004	0.55		5462	
	plastics	epoxy resin	-	0.055	7.37		73748	
	inorganic material	silicondioxide	60676-86-0	0.349	46.72	54.64	467075	546285
leadfinish	noble metal	gold	7440-57-5	0.010	1.29	1.29	12919	12919
plating	noble metal	silver	7440-22-4	0.016	2.11	2.11	21097	21097
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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